

SID

Factory: Rot am See

Article:

ML4

Provided:

Customer:

Date:

31.03.2026

WÜRTH  
ELEKTRONIK  
MORE THAN  
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1		
C-RAS-FR4-PP-2116_H50-TG150HF-gel-PAN...	50202536	412		2		
C-RAS-FR4-PP-7628-TG150HF-gel-PAN-R15...	50202586	0		3		
C-RAS-FR4-PP-2116_H50-TG150HF-gel-PAN...	50202536	0		4		
		70	L2			
C-RaS-FR4-DS-0.991mm-070+070-TG150-HF...	50203142	850		5	A00	B00
		70	L3			
C-RAS-FR4-PP-2116_H50-TG150HF-gel-PAN...	50202536	412		6		
C-RAS-FR4-PP-7628-TG150HF-gel-PAN-R15...	50202586	0		7		
C-RAS-FR4-PP-2116_H50-TG150HF-gel-PAN...	50202536	0		8		
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	9		

Thickness after Pressing

B00: 1890 µm Tol+: 200 µm Tol-: 200 µm Dmax: 2090 µm Dmin: 1690 µm

Thickness over all

0 µm Tol+: 0 µm Tol-: 0 µm Dmax: 0 µm Dmin: 0 µm

Demand for customer

Thickness (D): 2000 µm Tol+: 200 µm Tol-: 200 µm Dmax: 2200 µm Dmin: 1800 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal: 1850 µm

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